INVITATION

TECH day

Microelectronics

HOW SMALL CAN WE GO ?

The challenges of going smaller on your dispensing & wire bonding

Explore the depths of innovative packaging technology during our exclusive free to attend Tech Day.

Meet the experts,
attend insightful talks, and see live demonstrations of cutting-edge equipment in action.

Join us on 10th of December
at our Linton, Cambridge facility

👉 **PLACES ARE LIMITED**

Confirm your attendance now!

sales@accelonix.co.uk

AGENDA OF THE DAY

A day designed for learning, exploring and networking

09:30 – Arrival, Coffee & Informal Networking

10:00 – Accelonix Introduction
Scott Wood, Accelonix UK & Ireland

10:15 – TPT: Wirebonding technology introduction

Case Study 1: How does selecting the type of bond affect how small you can go?
Fabian Hickmann, TPT

10:45 – Musashi: Technology introduction

Case Study 2: What happens when precision meets pressure? Inside micro dispensing.
Okuyama Kaoru, Musashi Engineering

11:15 – Coffee break

11:45 – A.M. Case study demonstrations by group rotation including:
Dispensing, wire bonding & non-contact surface metrology with CyberTechnologies

12:45 – Buffet Lunch & Informal Networking

13:45 – TPT Presentation

Case Study 3: What if special tools could let you go small with your interconnects?
Stefan Kaltenbach, TPT

14:15 – Musashi Presentaiton

Case Study 4: Can speed still be precise? Jet dispensing below 100 microns
Okuyama Kaoru, Musashi Engineering

13:55 – Coffee break

15:15 – P.M. Case study demonstrations by group rotation including:
Dispensing, wire bonding & 3D X-Ray with Comet Yxlon

16:15 – Final Remarks

Accelonix
keeping you ahead

accelonixuk&ireland www.accelonix.co.uk

LIVE EQUIPMENT DEMONSTRATIONS

1- Musashi Engineering: Image Master 350 PC, Super Sigma CMIV & Super Jet 2 – Dispensing

2- TPT: HB05, HB16 & HB100 – Wire bonding

3- Comet Yxlon: Cheetah EVO – 3D X-Ray Inspection

4- CyberTechnologies: CT300 – Non-Contact Surface Metrology

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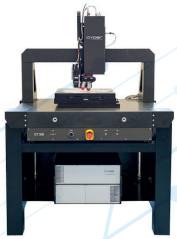

GUEST SPEAKERS

Okuyama Kaoru
Managing director at Musashi Engineering Europe

Extensive experience within the micro-dispensing industry, Mr Okuyama leads Musashi Engineering Europe in delivering high-precision, micro-dosage dispensing solutions across a wide range of industrial applications.

Fabian Hickmann
Production Manager at TPT

Over 20 years of experience in the wire bonding industry, having supported numerous projects across a wide range of applications. Expertise encompassing application support, prototyping, and small-volume production.

Stefan Kaltenbach
Sales Manager at TPT

Experienced technical sales specialist within the machine and tooling industry. Expert in defining the optimal machine and tooling configurations for each specific wire bonding application for the global market.

⊕ ALSO ON DISPLAY

Fully automatic wire bonder & die bonders ,Semi-automatic heavy wire bonder, Semi-automatic die sorter, Laser Marker, 3D AOI system, Smart assembly station, Smart racking & Flying probe measurement testing system.

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